



NOTES:

1.MATERIAL:

1.1 HOUSING: THERMOPLASTIC, HIGH TEMP.,UL94V-0.
COLOR:NATURAL.

1.2 CONTACT: COPPER ALLOY.

2.FINISH:

2.1 CONTACT:

C:50~100u" NICKEL UNDERPLATING OVERALL.

CONTACT AREA: GOLD 15u" MIN

SOLDER TAIL: GOLD 1u" MIN

2:50~100u" NICKEL UNDERPLATING OVERALL.

CONTACT AREA: GOLD FLASH OVERALL

SOLDER TAIL: GOLD FLASH OVERALL

N:50u"~100u" NICKEL OVERALL

100~180u" MATT TIN OVERALL

3.REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.

4.SPEC.PLS REFER TO PS-51210-XXXX-XXX

5.PART NUMBER

| XXX | LOGO | DIMG | PACKING |
|-----|------|------|-------------------|
| 001 | ACES | 3.50 | / |
| 002 | ACES | 1.10 | 51209-XXXX-06-TRP |
| 003 | ACES | 2.10 | / |
| 004 | ACES | 2.10 | 51209-XXXX-XX-TRP |
| 008 | ACES | 1.80 | 51209-XXXX-07-TRP |
| 005 | ACES | 2.60 | 51209-XXXX-05-TRP |

CKTS
PACKING
1:TUBE
3:BAG
0:TAPE REEL
4:TAPE&REEL WITH MYLAR
7:TAPE&REEL WITH COVER

PLATING

C:CONTACT AREA: GOLD 15u" MIN

SOLDER TAIL: GOLD 1u" MIN

2:GOLD FLASH OVERALL

N: MATT TIN ON CONTACT FOR LEAD FREE

| CKTS | DIMA | DIMB | DIMC | DIMD | DIME | DIMF | M/S (H) |
|------|-------|-------|-------|-------|-------|-------|---------|
| 003 | 8.00 | 6.74 | 5.58 | 4.00 | 3.10 | 2.00 | 8.00 |
| 004 | 10.00 | 8.74 | 7.58 | 6.00 | 5.10 | 4.00 | 10.0 |
| 006 | 14.00 | 12.74 | 11.58 | 10.00 | 9.10 | 8.00 | XX |
| 007 | 16.00 | 14.74 | 13.58 | 12.00 | 11.10 | 10.00 | XX |
| 010 | 22.00 | 20.74 | 19.58 | 18.00 | 17.10 | 16.00 | XX |
| 012 | 26.00 | 24.74 | 23.58 | 22.00 | 21.10 | 20.00 | XX |

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| QUALITY SYMBOLS MAJOR Ⓢ CRITICAL Ⓢ GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2° | DRAWN BY DENGJIMIN DATE 24/04/08 | | |
| | CHECKED BY XUZHUYONG DATE 24/04/08 | | TITLE 2.00mm WTB WAFER CONN. T/H S/T TYPE |
| APPROVED BY XUZHUYONG DATE 24/04/08 | UNITS mm | SIZE A4 | RFO NO. NA |
| SCALE 5:1 | SHEET NO. 1 OF 1 | REV K | DWG NO. 51209-XXXX-XXX |